

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>David Chong</td> <td>06/10/2003</td> </tr> <tr> <td>Hun Kwang Lee</td> <td>04/26/2003</td> </tr> </tbody> </table>		Name	Execution Date	David Chong	06/10/2003	Hun Kwang Lee	04/26/2003
Name	Execution Date						
David Chong	06/10/2003						
Hun Kwang Lee	04/26/2003						
RECEIVING PARTY DATA							
Name:	Fairchild Semiconductor Corporation						
Street Address:	82 Running Hill Road, MS 35-4E						
City:	South Portland						
State/Country:	MAINE						
Postal Code:	04106						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10397436</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10397436		
Property Type	Number						
Application Number:	10397436						
CORRESPONDENCE DATA							
Fax Number:	(801)321-4893						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
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Correspondent Name:	Kenneth E. Horton						
Address Line 1:	60 East South Temple						
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ATTORNEY DOCKET NUMBER:	11948.18						
NAME OF SUBMITTER:	Kenneth E. Horton						
Total Attachments: 2 source=Assignment11948_18#page1.tif source=Assignment11948_18#page2.tif							

CH \$40.00 10397436

ASSIGNMENT

For valuable consideration, the receipt and adequacy of which is hereby acknowledged, and in fulfillment of our pre-existing obligation of assignment, we, **David Chong and Hun Kwang Lee**, of **2S, Cangkat Sg Ara 3, Desa Ara, Bayan Lepas, Penang, Malaysia, 11900; and 3, Tingkat Betek 2, Sg. Rambai, 14000 Bkt. Mertajam, Penang, Malaysia**, respectively, sell and assign to Fairchild Semiconductor Corporation, a Corporation of the state of Delaware, its successors and assigns the entire right, title and interest in and to the improvements "**PACKAGING SYSTEM FOR SEMICONDUCTOR DEVICES**" (Docket No. **40013-0018**) invented by us, as described in the application for United States patent filed on **March 25, 2003 (Ser No. # 10/397,436)**, and any and all applications for patent and patents therefor in any and all countries, including all divisions, reissues, continuations and extensions there of, and all rights of priority resulting from the filing of said United States application, and authorize and request any official whose duty it is to issue patents, to issue any patent on said improvements or resulting therefrom to said Fairchild Semiconductor Corporation., or its successors or assigns and agree that on request and without further consideration, but at the expense of said Corporation, we will communicate to said Corporation or its representatives or nominees any facts known to us respecting said improvements and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Corporation, its successors, assigns, and nominees to obtain and enforce proper patent protection for said improvements in all countries.

The aforementioned Assignors, **David Chong and Hun Kwang Lee**, hereby declare that all statements made herein of our own knowledge are true and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signed at town of Bayan Lepas, Penang, Mal., this 10 day of June, 2003.

Witnessed by: Jaduliy 10/6/03 David Chong
Witness Signature & Date
COLETO3-FEL TAN.
Printed Name of Witness

Signed at town of _____, this _____ day of _____, 2003.

Witnessed by: _____ Hun Kwang Lee
Witness Signature & Date

Printed Name of Witness

ASSIGNMENT

For valuable consideration, the receipt and adequacy of which is hereby acknowledged, and in fulfillment of our pre-existing obligation of assignment, we, **David Chong and Hun Kwang Lee**, of **2S, Cangkat Sg Ara 3, Desa Ara, Bayan Lepas, Penang, Malaysia, 11900; and 3, Tingkat Betek 2, Sg. Rambai, 14000 Bkt. Mertajam, Penang, Malaysia**, respectively, sell and assign to Fairchild Semiconductor Corporation, a Corporation of the state of Delaware, its successors and assigns the entire right, title and interest in and to the improvements "**PACKAGING SYSTEM FOR SEMICONDUCTOR DEVICES**" (Docket No. 40013-0018) invented by us, as described in the application for United States patent filed on **March 25, 2003 (Ser No. # 10/397,436)**, and any and all applications for patent and patents therefor in any and all countries, including all divisions, reissues, continuations and extensions there of, and all rights of priority resulting from the filing of said United States application, and authorize and request any official whose duty it is to issue patents, to issue any patent on said improvements or resulting therefrom to said Fairchild Semiconductor Corporation., or its successors or assigns and agree that on request and without further consideration, but at the expense of said Corporation, we will communicate to said Corporation or its representatives or nominees any facts known to us respecting said improvements and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Corporation, its successors, assigns, and nominees to obtain and enforce proper patent protection for said improvements in all countries.


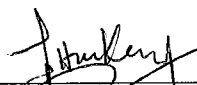
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Signed at town of _____, this _____ day of _____, 2003.

Witnessed by: _____
Witness Signature & Date **David Chong**

Printed Name of Witness

Signed at town of BUKIT MERTAJAM, PENANG, this 26th day of APRIL, 2003.

Witnessed by:  24/04/03  24/04/03
Witness Signature & Date **Hun Kwang-Lee**
NG SAIK HONG
Printed Name of Witness